

Publikationen

(1998): Low dielectric constant materials for interlayer dielectric. (Invited Paper). In: Microelectronic Engineering, vol. 40, no. 1, pp. 1-19. DOI: 10.1016/S0167-9317(97)00185-8.

(1997): Dielectric Materials and Insulators for Microelectronics. In: Chemical vapor deposition, Pennington, NJ, vol. 97-25.

(1997): High-Temperature Resistent Devices for Energy-Efficient Automotive Applications. In: Proceedings of the 30th International Symposium on Automotive Technology and Automation 1997 (ISATA).

(1996): Metallisierung höchstintegrierter und komplexer Systeme. (Eingeladener Beitrag). In: Verhandlungen der DPG (VI), vol. 31.

(1996): Future Challenges in Multilevel Interconnection and Wiring. In: Proceedings of the 8th Dielectrics and CVD Metallization Symposium (San Diego, CA, USA; March 1996).